



Material Content Data Sheet



Sales Product Name		TLE7270-2D		Issued		28. August 2013		
MA#		MA000669534						
Package		PG-TO252-5-11		Weight*		356.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.671	0.47	0.47	4688	4688
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		574	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.29	57.37	572897	573643
wire	non noble metal	aluminium	7429-90-5	0.181	0.05	0.05	507	507
encapsulation	organic material	carbon black	1333-86-4	1.417	0.40		3974	
	plastics	epoxy resin	-	24.792	6.95		69541	
	inorganic material	silicondioxide	60676-86-0	115.460	32.39	39.74	323862	397377
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14228	14228
plating	non noble metal	nickel	7440-02-0	0.076	0.02		214	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	215
solder	noble metal	silver	7440-22-4	0.083	0.02		234	
	non noble metal	tin	7440-31-5	0.067	0.02		187	
	non noble metal	lead	7439-92-1	3.180	0.89	0.93	8921	9342
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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